



**REGISTER NOW**

**July 25-30, 2021**

**The 13th International Conference on the  
Technology of Plasticity (ICTP 2021)**

**VIRTUAL EVENT**



**DISCOUNT REGISTRATION DEADLINE: JUNE 17, 2021**

From fundamental science to industrial application, the breadth of the metal forming community will convene at The 13th International Conference on the Technology of Plasticity (ICTP 2021). Scientists and engineers from across industry, academia, and government will share their latest improvements and innovations in all aspects of metal forming science and technology, with the intent of facilitating linkages and collaborations among these groups.

**DON'T MISS THIS OPPORTUNITY TO LEARN FROM AND CONNECT WITH LEADERS IN METAL FORMING.**

International experts will deliver keynote talks on global issues, simulation, materials, and innovation. Honorary symposia will recognize seven distinguished individuals. Topics of particular interest include, but are not limited to:

- Metal Forming Processes & Equipment
- Joining by Forming and Deformation
- Microstructure and Damage Development & Characterization
- Big Data and Metal Forming
- High Speed and Impulse Forming
- Agile Metal Forming
- Microstructure Development by Forming
- Technologies to Speed Innovation
- Value of, and Limits to, Simulation

Learn more about the technical topics planned for this congress at [www.tms.org/ICTP2021](http://www.tms.org/ICTP2021).

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**REGISTER BY JUNE 17, 2021 FOR DISCOUNTED RATES AT:**

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